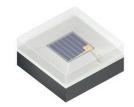
SFH 4170S A01

OSLON® Piccolo

High Power Infrared Emitter (850 nm)











Applications

- Access Control (IRIS/Vein Scan, Face Recognition)
- Driver Monitoring / Seat Occupancy Detection
- Eye Tracking
- Gesture Recognition
- Safety and Security, CCTV

Features:

- Package: clear silicone

- Corrosion Robustness Class: 3B

- Qualifications: AEC-Q102 Qualified

- ESD: 2 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM)

- IR lightsource with high efficiency

- Double stack emitter

- Centroid wavelength 850 nm

Ordering Information

Туре	Total radiant flux 1)2)	Total radiant flux 1) typ.	Ordering Code
	$I_{F} = 1 \text{ A}; t_{p} = 10 \text{ ms}$ Φ_{p}	$I_{\rm F} = 1 \text{ A}; t_{\rm p} = 10 \text{ ms}$ $\Phi_{\rm p}$	
SFH 4170S A01	1000 1400 mW	1,150 mW	Q65112A9015



Maximum Ratings

$T_{\scriptscriptstyle \wedge}$	=	25	$^{\circ}C$

Parameter	Symbol		Values
Operating temperature	T _{op}	min.	-40 °C
	GP.	max.	105 °C
Storage temperature	T _{stg}	min.	-40 °C
	3.19	max.	105 °C
Junction temperature	T_j	max.	145 °C
Forward current	I _F	max.	1000 mA
Surge current	I _{FSM}	max.	2 A
$t_p \le 600 \mu\text{s}; D = 0.005$			
Reverse voltage 3)	V_R	max.	5 V
Power consumption	P _{tot}	max.	3600 mW
ESD withstand voltage	V_{ESD}	max.	2 kV
acc. to ANSI/ESDA/JEDEC JS-001 (HBM)	200		

Note: For the forward current and power consumption please see "maximum permissible forward current" diagram.



Characteristics

 $I_{\scriptscriptstyle F}$ = 1000 mA; $t_{\scriptscriptstyle p}$ = 10 ms; $T_{\scriptscriptstyle A}$ = 25 °C

Parameter	Symbol		Values	
Peak wavelength	$\lambda_{ m peak}$	typ.	860 nm	
Centroid wavelength	$\lambda_{ ext{centroid}}$	typ.	850 nm	
Spectral bandwidth at 50% I _{rel,max} (FWHM)	Δλ	typ.	30 nm	
Half angle	φ	typ.	65 °	
Dimensions of chip area	L×W	typ.	0.73 x 0.73 mm x mm	
Rise time (10% / 90%) $I_F = 2 \text{ A}; R_L = 5 \Omega$	t,	typ.	9 ns	
Fall time (10% / 90%) $I_F = 2 A; R_L = 5 \Omega$	t _f	typ.	16 ns	
Forward voltage 4)	V_{F}	typ. max.	3.25 V 3.6 V	
Forward voltage ⁴⁾ $I_F = 2 \text{ A}; t_p = 100 \mu\text{s}$	V_{F}	typ. max.	3.7 V 4.2 V	
Reverse current $^{3)}$ $V_R = 5 V$	I _R	typ. max.	0.01 μA 10 μA	
Radiant intensity 5)	l _e	typ.	280 mW/sr	
Temperature coefficient of voltage	TC_v	typ.	-2 mV / K	
Temperature coefficient of wavelength	TC,	typ.	0.3 nm / K	
Thermal resistance junction solder point electrical $^{6)}$ with efficiency η_e = 38 %	$R_{ ext{thJS elec.}}$	typ. max.	6.8 K / W 8.1 K / W	
Thermal resistance junction solder point real ⁶⁾	$R_{thJSreal}$	typ. max.	11.0 K / W 13.0 K / W	

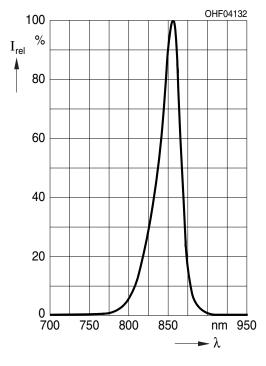


Brightness Groups

Group	Total radiant flux $^{1)2)}$ $I_F = 1 \text{ A}$; $t_p = 10 \text{ ms}$ min. Φ_e	Total radiant flux $^{1)2)}$ I _F = 1 A; t _p = 10 ms max. Φ_e
EB2	1000 mW	1120 mW
FA1	1120 mW	1250 mW
FA2	1250 mW	1400 mW

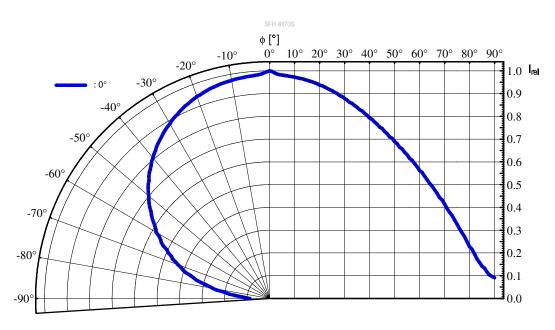
Relative Spectral Emission 7), 8)

 $I_{e,rel} = f(\lambda); I_{F} = 1000 \text{ mA}; t_{p} = 10 \text{ ms}$



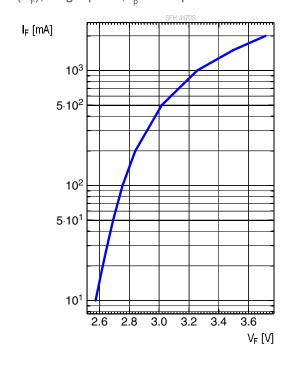
Radiation Characteristics 7), 8)

$$I_{e,rel} = f(\phi)$$



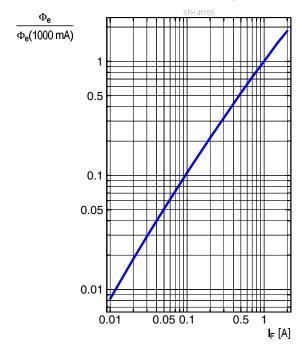
Forward current 7), 8)

 $I_F = f(V_F)$; single pulse; $t_p = 100 \mu s$



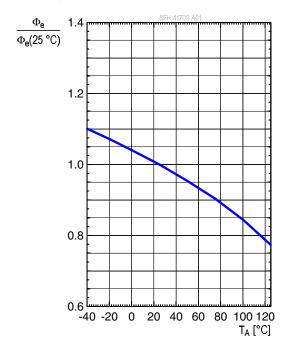
Relative Total Radiant Flux 7), 8)

 $\Phi_{\rm e}/\Phi_{\rm e}(1000{\rm mA})$ = f (I_F); single pulse; t_p = 100 $\mu {\rm s}$



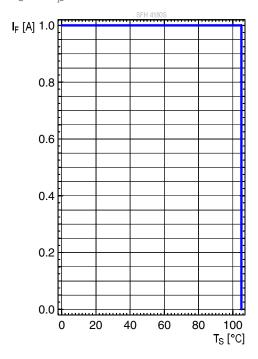
Relative Total Radiant Flux 7)

$$\Phi_{\rm e}$$
 = f (T_A); t_p = 100 µs; I_F = 1000 mA



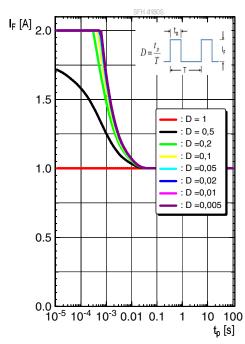
Max. Permissible Forward Current

$$I_{F,max} = f(T_S); Rth_{js} = 13K/W$$

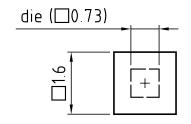


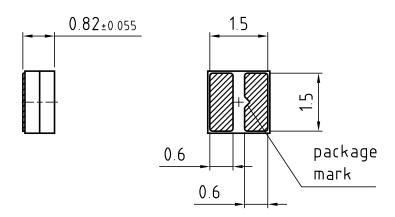
Permissible Pulse Handling Capability

 $I_F = f(t_p)$; duty cycle D = parameter; $T_S = 85$ °C



Dimensional Drawing 9)





general tolerance ± 0.05 lead finish Au ZZZZ

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Further Information:

Approximate Weight: 6.2 mg

Package marking: Cathode

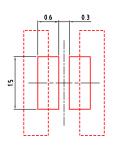
Corrosion test: Class: 3B

Test condition: 40°C / 90 % RH / 15 ppm H₂S / 14 days (stricter than IEC

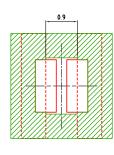
60068-2-43)



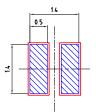
Recommended Solder Pad 9)











solder stencil recommended stencil thickness 120µm

Component Location on Pad



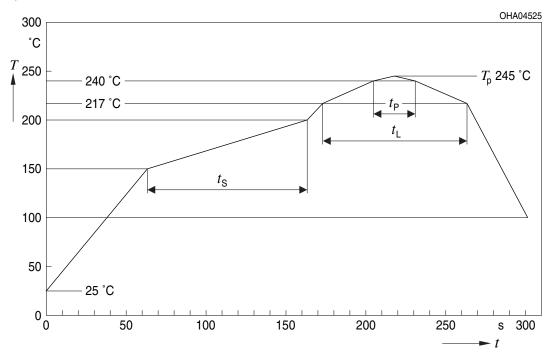




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Reflow Soldering Profile

Product complies to MSL Level 2 acc. to JEDEC J-STD-020E



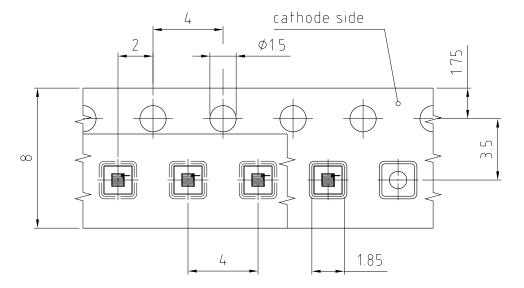
Profile Feature	Symbol	Pb-Free (SnAgCu) Assembly			Unit
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat*)			2	3	K/s
25 °C to 150 °C					
Time t _s	$t_{\scriptscriptstyle{S}}$	60	100	120	S
T_{Smin} to T_{Smax}					
Ramp-up rate to peak*)			2	3	K/s
T_{Smax} to T_{P}					
Liquidus temperature	T_{L}		217		°C
Time above liquidus temperature	$t_{\scriptscriptstyle L}$		80	100	S
Peak temperature	T_{P}		245	260	°C
Time within 5 °C of the specified peak temperature T _P - 5 K	t _P	10	20	30	S
Ramp-down rate*			3	6	K/s
T _P to 100 °C					
Time				480	S
25 °C to T _P					

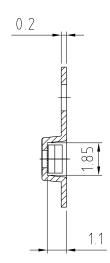
All temperatures refer to the center of the package, measured on the top of the component



^{*} slope calculation DT/Dt: Dt max. 5 s; fulfillment for the whole T-range

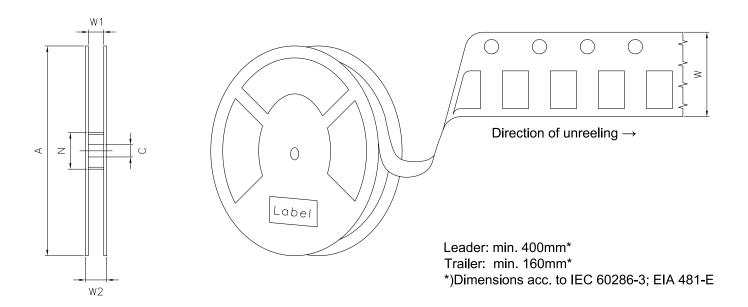
Taping 9)





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Tape and Reel 10)



Reel Dimensions

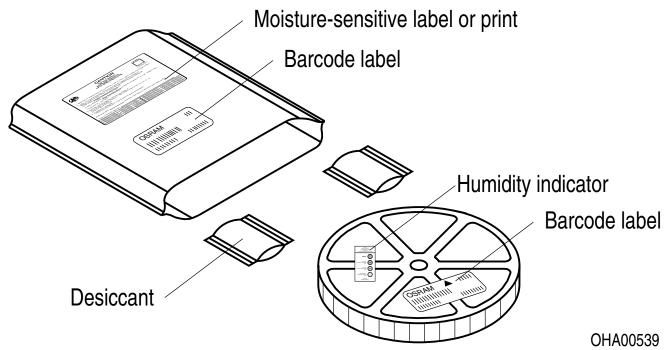
Α	W	N_{\min}	W_1	$W_{2 \text{ max}}$	Pieces per PU
180 mm	8 + 0.3 / - 0.1 mm	60 mm	8.4 + 2 mm	14.4 mm	4000



Barcode-Product-Label (BPL)



Dry Packing Process and Materials



Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.



Notes

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the device specified in this data sheet fall into the class **exempt group (exposure time 10000 s)**. Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this device contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize device exposure to aggressive substances during storage, production, and use. Devices that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

Handling:

Solvents, water, liquids, non-conductive plastics and glues are not allowed near the device, because solvents and other liquids could emerge and damage the product.

For further application related information please visit www.osram-os.com/appnotes



Disclaimer

Attention please!

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version on the OSRAM OS website.

Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

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OSRAM OS components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.

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Glossary

- 1) **Total radiant flux:** Measured with integrating sphere.
- Brightness: The brightness values are measured with a tolerance of $\pm 11\%$.
- Reverse Operation: This product is intended to be operated applying a forward current within the specified range. Applying any continuous reverse bias or forward bias below the voltage range of light emission shall be avoided because it may cause migration which can change the electro-optical characteristics or damage the LED.
- Forward Voltage: The forward voltages are measured with a tolerance of ±0.1 V.
- Radiant intensity: Measured at a solid angle of Ω = 0.01 sr
- Thermal resistance: junction soldering point, of the device only, mounted on an ideal heatsink (e.g. metal block)
- Typical Values: Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- ⁸⁾ **Testing temperature:** TA = 25°C (unless otherwise specified)
- Tolerance of Measure: Unless otherwise noted in drawing, tolerances are specified with ±0.1 and dimensions are specified in mm.
- ¹⁰⁾ **Tape and Reel:** All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.



SFH 4170S A01

Revision	Revision History		
Version	Date	Change	
1.0	2020-05-14	Initial Version	
1.1	2021-01-16	Product Image Taping	
1.2	2021-10-25	Characteristics Dimensional Drawing	



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